

PCN#: P56GAAB

Issue Date : Jul. 15, 2015

## **Information Only Notification**

This is to inform you that a change is being made to the following products.

This is a minor change that has no impact on product quality, reliability, electrical or mechanical performance. Affected products will remain fully compliant to all published specifications. Notification is being made for informational purposes only and there is no approval required. Products incorporating this change may be shipped interchangeably with existing unchanged products.

Please contact your local Customer Quality Engineer if you have any questions regarding this notification. Alternatively, you may send an email request for information to PCNSupport@fairchildsemi.com.

#### **Implementation of change:**

Description of Change (From):
Old thermal board images in datasheet (Page 2)



1. R<sub>QLA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>QLC</sub> is guaranteed by design while R<sub>GCA</sub> is determined by the user's board design.



a. 78 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



b.175 °C/W when mounted on a minimum pad of 2 oz copper

B

- 2. Pulse Test: Pulse Width < 300  $\mu s,$  Duty cycle < 2.0 %.
- 3. As an N-ch device, the negative Vgs rating is for low duty cycle pulse occurrence only. No continuous rating is implied.

# Description of Change (To):

## New thermal board images in datasheet (page 2)

NOTES:

1. R<sub>BJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>BJC</sub> is guaranteed by design while R<sub>BCA</sub> is determined by the user's board design.



- 2. Pulse Test: Pulse Width < 300 μs, Duty cycle < 2.0 %.
- 3. As an N-ch device, the negative Vgs rating is for low duty cycle pulse occurrence only. No continuous rating is implied.

## Reason for Change:

Update thermal board images to match the board used in test.

Affected Product(s): Please refer to the list of affected products in the addendum attached in the PCN email you received. This list is based on an analysis of your company's procurement history.